MSKSEMI 美森科













ESD

1/5

TSS

MOV

GDT

PIFD

LC03-6-MS

Product specification





Features

Ultra low leakage: nA level

Operating voltage: 6V

Low clamping voltage

Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

Air discharge: ±30kV

Contact discharge: ±30kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

- IEC61000-4-5 (Lightning) 100A (8/20µs)

RoHS Compliant

Mechanical Characteristics

• Package: SOP--8

Lead Finish: Lead Free

• UL Flammability Classification Rating 94V-0

Quantity Per Reel:500pcs

Reel Size:7 inch

Applications

USB 2.0 power and data line

Set-top box and digital TV

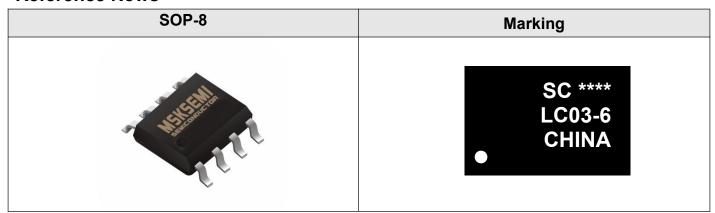
Digital video interface (DVI)

Notebook Computers

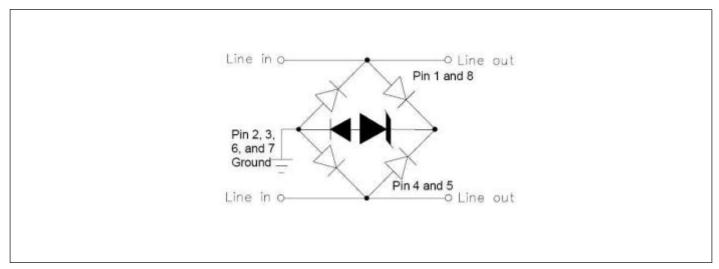
SIM Ports

• 10/100 Ethernet

Reference News



Pin Configuration





Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20µs)	Ррр	2000	W	
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 30	Kv	
ESD per IEC 61000-4-2 (Contact)		± 30		
Operating Temperature Range	TJ	-55 to +125	°C	
Storage Temperature Range	Тѕтл	-55 to +150	$^{\circ}$	

Electrical Characteristics(TA=25°C unless otherwise specified)

	V _{RWM}	V _{BR}	ŀr	V c	Vc		µA (Max)	(Pf) (T Ç p.)
Part Number	(V)	(V)	(mA)	@50A	(Max)	(@A)	(Max)	
LC03-6-MS	6	6.8	1	15	20	100	25	25



Characteristic Curves

Fig1. 8/20 µs Pulse Waveform

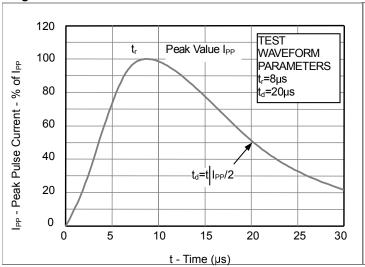


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

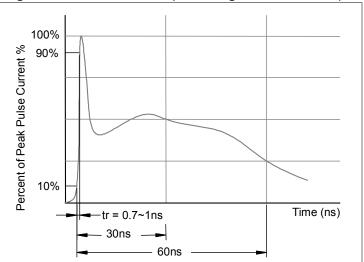
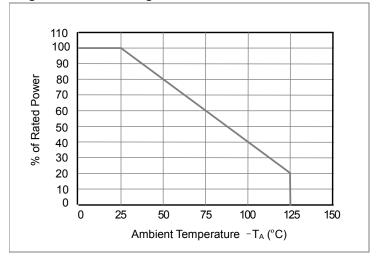
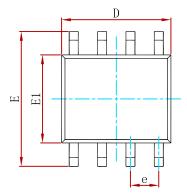


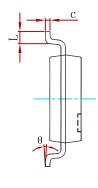
Fig3. Power Derating Curve

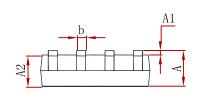




PACKAGEMECHANICALDATA

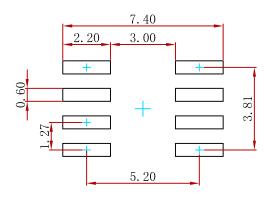






Symbol	Dimensions In	Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0. 100	0. 250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0. 510	0.013	0.020	
c	0. 170	0. 250	0.007	0.010	
D	4.800	5. 000	0. 189	0. 197	
e	1.270 (BSC)		0.050 (BSC)		
E	5. 800	6. 200	0. 228	0. 244	
E1	3.800	4. 000	0. 150	0. 157	
L	0.400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	

Suggested Pad Layout



- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

Order information

Orderable Device	Package	Packing Option
LC03-6-MS	SOP-8	500PCS



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